

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	1.36334	100.0	1.6
			Subtotal	1.36334	100	1.6
Wire	Impurity	Non hazardous		0.00001	0.01	0.00001
	Pure metal	Copper (Cu)	7440-50-8	0.0671	99.99	0.07874
			Subtotal	0.06711	100	0.07875
Die Attach		Aromatic Polyester Resin	60088-52-0	0.00277	2.5	0.00325
		Paraffin wax	8002-74-2	0.00775	7.0	0.0091
		Epoxy resin system		0.02215	20.0	0.026
		Silver (Ag)	7440-22-4	0.07809	70.5	0.09165
			Subtotal	0.11076	100	0.13
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02601	0.05	0.03053
	Copper alloy	Zinc (Zn)	7440-66-6	0.05202	0.1	0.06105
	Copper alloy	Iron (Fe)	7439-89-6	1.19646	2.3	1.40415
	Copper alloy	Copper (Cu)	7440-50-8	50.74549	97.55	59.55427
			Subtotal	52.01998	100	61.05
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.48569	100.0	0.57
			Subtotal	0.48569	100	0.57
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.6893	1.5	0.80895
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.36555	9.5	5.12335
	Filler	Silica fused	60676-86-0	40.43874	88.0	47.4584
	Carbon Black	Carbon black	1333-86-4	0.45953	1.0	0.5393
			Subtotal	45.95312	100	53.93
			Total	100	100	117.35875

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.